

Investor Presentation

May 2023

Disclaimer



This presentation contains forward-looking statements relating to the business, financial performance and earnings of SÜSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SÜSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SÜSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.

May, 2023 $\mathbf{2}$

Agenda



O1 Introduction

Q1 2023 and Outlook 2023

O3 Ambition 2030

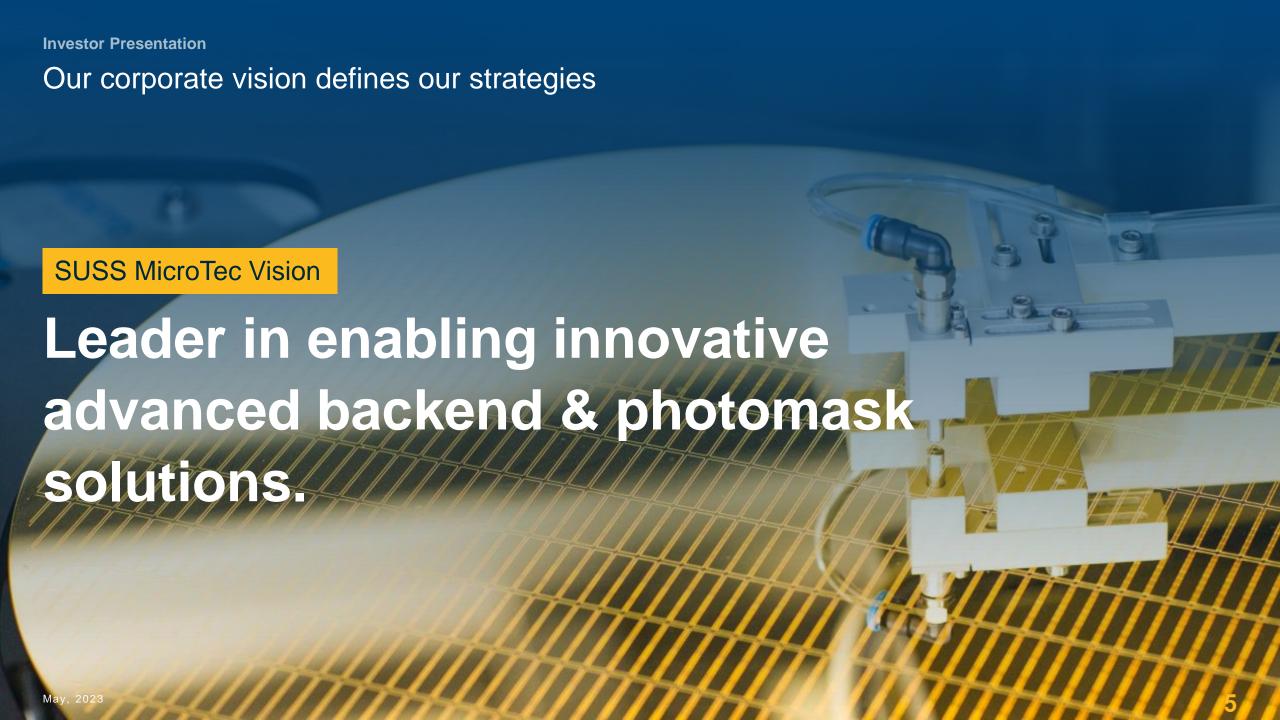




SUSS MicroTec at a glance

- Hidden champion headquartered in Germany with 70+ year track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities
- 2025 Target: more than € 400 million revenue and >15% EBIT margin

SUSS is part of our digital life!



Our world are the semiconductor frontend and backend process steps



Wafer fabrication

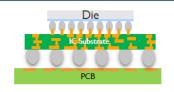


Front-end-of-line Wafer process



- Deposition/coating
- Cleaning
- Patterning/lithography¹
- Etching
- Implantation
- Annealing
- Permanent bonding
- Temporary bonding
- CMP polishing

From middle-of-line to back-end-of-line Advanced packaging



- Deposition/coating
- Cleaning
- Patterning/lithography
- Etching
- Annealing
- CMP polishing
- Permanent bonding
- Temporary bonding
- Wafer-level packaging
- Wafer dicing
- Panel-level packaging

Final packaging



- Mounting
- Wire bonding
- Molding encapsulation
- Trim & forming

Only related to Photomask processing Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

Products

Advanced Backend Solutions as core asset in our product portfolio



Frontend

Segments Photomask Equipment





Photomask



MaskTrack X

Advanced backend

Advanced Backend Solutions¹



Imaging





Coating



Bonding

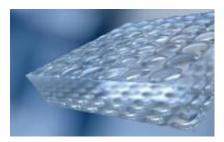
XBC300

XB8

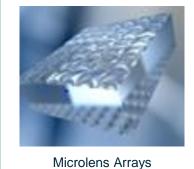
ACS300

Components

MicroOptics







¹⁾ Business units Lithography and Bonder were merged into the new Advanced Backend Solutions business unit at the end of 2022. We will report in the new structure from the 2023 financial year onwards.

Agenda



01 Introduction

Q1 2023 and Outlook 2023

O3 Ambition 2030

Dynamic order momentum, but targeted margins not yet achieved in Q1 2023



Financial Results Q1 2023

99.6

in € million

Order Entry Q1 2023 70.4

in € million

Sales Q1 2023 33.1

in %

Gross profit margin Q1 2023 4.1

in %

EBIT Margin Q1 2023

Guidance for all three key financial indicators confirmed

Investor Presentation

Business Highlights Q1 2023



- Order entry remains strong despite generally expected slowdown in orders from semiconductor industry
- Sales up by 11.2% compared to last year; Photomask Solutions as main growth driver (business almost tripled)
- Challenging margin situation in Q1 2023, but better product mix and higher sales volume expected during the course of the year 2023
- Change in cost allocation from Q1 2023 onwards: costs for application centers shifted from SGA to R&D costs with an expected effect of ~ € 6 million in 2023
- Status of main R&D projects: integrated D2W hybrid bonder and wafer cleaner currently being installed at Sternenfels application center; first customer demonstrations are most likely to be carried out in the third quarter of 2023

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In € million	Q1 2023	Q1 2022	Change
Order entry	99.6	117.6	-15.3%
Order backlog as of March 31	373.2	249.2	49.8%
Sales	70.4	63.3	11.2%
Gross profit	23.3	21.0	10.8%
Gross profit margin	33.1%	33.2%	-0.1%pts
EBIT	2.9	2.1	38.1%
EBIT margin	4.1%	3.3%	0.8%pts
Earnings after tax	2.1	1.4	50.0%
Earnings per share, basic (in €)	0.11	0.07	57.2%
Net cash	41.0	35.2	16.5%
Free Cashflow	0.3	1.6	-81.3%
Employees as of March 31	1,261	1,194	5.6%



- Strong order entry and order backlog remain a solid foundation for targeted growth in 2023 and beyond
- Absolute gross profit and EBIT increased yoy
- Gross profit margin and EBIT margin within own expectation but not yet at target, mainly because of low margins in the bonder product lines and in MicroOptics
- Company has again created value for shareholders in Q1 2023 (earnings per share +57.2%)
- Net cash position increased once again due to higher prepayments

Order Entry by Division and Region

Order Entry by Division



Advanced Backend Solutions (since 2023)

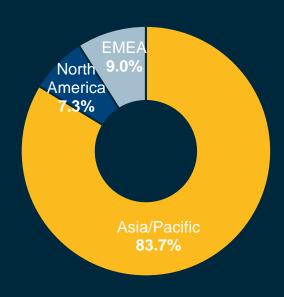




Order Entry by Region Q1 2023

Book-to-

bill-ratio



Division Overview Q1 2023



Advanced Backend Solutions

in € million	Q1 2023	Q1 2022
Order entry	56.2	69.5
 thereof Lithography 	44.8	49.4
- thereof Bonder	11.4	20.1
Total sales ¹	41.0	45.5
 thereof Lithography 	32.6	33.4
- thereof Bonder	8.4	12.1
Gross profit	14.9	15.9
Gross profit margin	36.3%	34.9%
EBIT	0.7	3.5
EBIT margin	1.7%	7.7%

Photomask Solutions

in € million	Q1 2023	Q1 2022
Order entry	38.6	40.9
Total sales ¹	23.1	7.8
Gross profit	7.0	2.1
Gross profit margin	30.3%	26.9%
EBIT	3.7	-1.4
EBIT margin	16.0%	-17.9%

MicroOptics

in € million	Q1 2023	Q1 2022
Order entry	4.7	7.1
Total sales ¹	6.9	10.6
Gross profit	1.4	3.1
Gross profit margin	20.3%	29.2%
EBIT	-1.1	0.7
EBIT margin	-15.9%	6.6%

- Decrease in order entry, mainly due to bonders and slightly lower demand for coaters; slight increase in orders for mask aligners
- Sales decreased by 9.9 percent because of lower sales level for automated permanent bonding systems compared to last year
- Gross profit margin increased due to good lithography margin
- Low EBIT margin as a result of low sales level and challenging bonder margins; higher R&D expenses for investments in future growth (especially hybrid bonding)

- Order entry remains on a high level
- Strong sales growth because of high backlog and ongoing strong demand in Asia
- Gross profit and EBIT margin improved strongly because of high sales level and a good product mix
- Q1 2023 saw a slow down in industrial applications
- Highly competitive automotive business
- Order entry and sales declined because of lower volume and price decreases from automotive customers
- Gross profit and EBIT declined accordingly

¹⁾ Total sales include internal sales (sales to other divisions) since 2021; gross profit margin and EBIT margin are calculated on the basis of total sales.

SUSS MicroTec

We expect to improve our three key performance indicators in 2023

Our Guidance 2023

We aim to take the next step on the way to our 2025 goals.







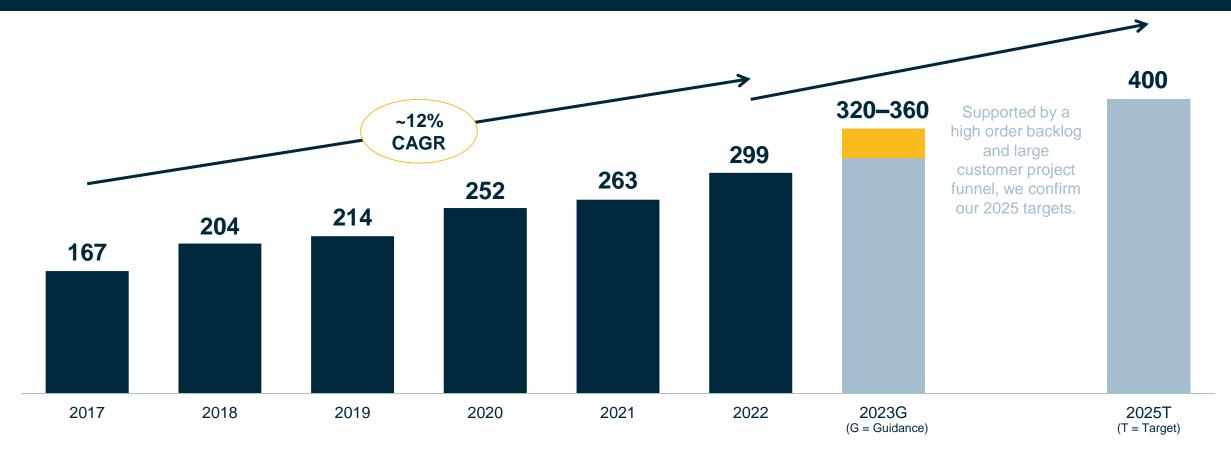
¹⁾ From 2023, we will use gross profit margin instead of free cash flow as the third performance indicator. For further information, please refer to the Annual Report.

²⁾ Including one-off effects of € 3.1 million. Operating EBIT margin thus accounted to 9.9%.

We aim to take the next step on the way to our 2025 goals



Our target 2025 Revenue of € 400 million with an EBIT margin of 15%



Agenda



01 Introduction

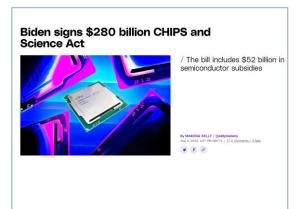
Q1 2023 and Outlook 2023

O3 Ambition 2030

Granted investment in global chip factories boosts semi equipment industry

















Bloomberg

Technology

Taiwan Passes Its Chips Act, Offers Tax Credits to Chipmakers

- A quarter of chip firms' R&D expenses can be deducted from tax
- Major governments are racing to build chip plants at home

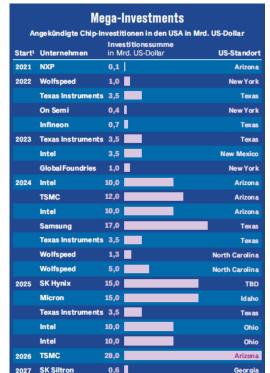
By Debby Wu

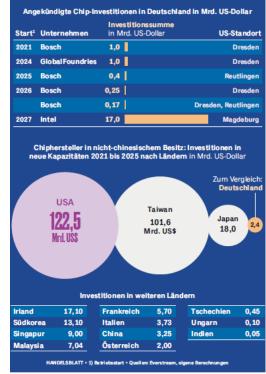
9. Januar 2023 um 03:26 MEZ *Updated on 9. Januar 2023 um 06:04 MEZ*

SÜSS MicroTec

Mid-term investment of the semiconductor industry is well filled







Summary of our strategic directives





Imaging Systems Mask Aligner

Scanner

Maintain business volume by increasing share and higher scanner penetration (against stepper)

Imprint

Gaining market share



Coating **Systems**

Coater (Spin, Spray)

Inkjet

Growth in line with the market

New growth opportunities with disrupting solution



Bonding Systems **Temporary Bonding**

Permanent Bonding

Growth in line with the market

Gaining market share

New growth opportunities with disrupting solution



Photomask Equipment

Photomask Equipment

(incl. Hybrid Bonding)

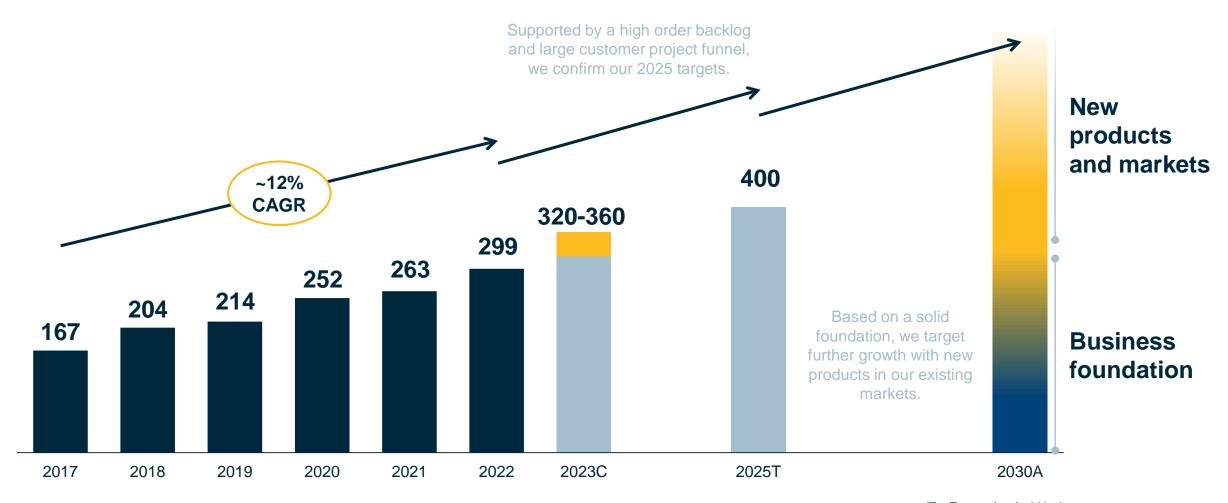
Wafer Cleaning

Growth in line with the market

New growth opportunities with disrupting solution

SÜSS MicroTec

Based on our business foundation we see further potential beyond



(T = Target, A = Ambition)

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Time for your questions...